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102372685

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1. Name of conveying party(ies):

KURATOMI, BUNSHI  
SHIMIZU, FUKUMI  
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NAMIKI, KATSUSHIGE  
MURAKAMI, FUMIO

2. 12 03

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies)

Name: 1. HITACHI, LTD.

2. Eastern Japan Semiconductor Technologies

Street Address: 1. 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo

2. 3-2, Fujihashi 3-chome, Ome-shi

City: 1. Tokyo 2. Tokyo

Country: Japan

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other \_\_\_\_\_

Execution Date: November 12, 11, 6, 5, 2003.

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

November 12, 11, 6, 5, 2003.

A. Patent Application No.(s)

B. Patent Registration No.(s)

10364503

Additional number(s) attached ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Antonelli, Terry, Stout & Kraus, LLP

Internal Address:

1300 North Seventeenth Street  
Suite 1800  
Arlington, VA 22209  
USA

City: State: Zip:

6. Total number of applications and patents involved 1

7. Total fee (37 CFR 3.41)..... \$40.00

☒ Enclosed

☐ Authorized to be charged to deposit account

8. Deposit account number:

01-2135

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*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

William I. Solomon, Reg# 28,565

02/12/03

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PATENT  
REEL: 013769 FRAME: 0995

# ASSIGNMENT

( 譲 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD. and Eastern Japan Semiconductor Technologies, Inc., corporations organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, and 3-2, Fujihashi 3-chome, Ome-shi, Tokyo, Japan, respectively, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD. and Eastern Japan Semiconductor Technologies, Inc., their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

## FABRICATION METHOD OF SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner ship of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD. and Eastern Japan Semiconductor Technologies, Inc., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD. and Eastern Japan Semiconductor Technologies, Inc.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

1) Bunshi Kuratomi (Bunshi KURATOMI)

12 / November / 2002

2) Fukumi Shimizu (Fukumi SHIMIZU)

11 / November / 2002

3) Kenichi Imura (Kenichi IMURA)

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06 / November / 2002

5) Fumio Murakami (Fumio MURAKAMI)

05 / November / 2002

6) \_\_\_\_\_

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7) \_\_\_\_\_

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